# BT-CCD Camera C8000-30

# **Back-Thinned CCD Camera**



#### ▲C8000-30

The C8000-30 employs an ultrahigh-sensitivity back-thinned CCD sensor made by Hamamatsu, which offers extremely high quantum efficiency in a wide range of UV, VIS and NIR wavelengths. The high UV sensitivity from 120 nm is useful for semiconductor mask inspection and measurement applications. Also, the high NIR sensitivity is useful for fluorescence measurement, NIR LD measurement and so on.





\* Without sapphire window. With the sapphire window, the spectral response is decreased due to the transmittance characteristics of the window.

### FEATURES

# High-sensitivity imaging from UV to nearinfrared wavelengths

- UV: Quantum efficiency over 60 % (at 200 nm)
- Near-infrared: Quantum efficiency over 90 % (at 650 nm)

#### Quantum efficiency in UV source (reference data)

			(Thi	s is typical, not guar	ranteed.)
Light source	F2	ArF	KrF	Fourth harmonic generation of a YAG laser	i line
Wavelength (nm)	157	193	248	266	365
Quantum efficiency (%) (typ.)	84	57	69	50	47

\* UV light irradiation may cause a drop in sensitivity and increase the dark current of the CCD sensor.

# Real time background subtraction

#### Recursive filter (2, 4, 8, 16, 32 and 64 frames selectable)

# PRINCIPLE

In a normal CCD with front-illuminated CCD structure, the light sensitive pixels have a charge transfer function as well, and this function requires the front surface of light sensitive pixels to be covered by a semi-transparent Poly-Si electrode for the charge transfer function. The Poly-Si electrode absorbs some percentage of incoming photons depending on their wavelength. Especially of of the UV light is not able to reach the light sensitive pixels.

To overcome this disadvantage, in a back-thinned CCD, the CCD is turned upside down and this back side of the CCD is thinned to 10-15  $\mu$ m in thickness. Incident photons now enter the CCD from the back-thinned side, without the Poly-Si electrode in the light path. Then QE values of greater than 90 % can be achieved.



#### SYSTEM CONFIGURATION





# SYSTEM SPECIFICATIONS

Type numbe	r		C8000-30			
Imaging dev	ice		Back-thinned frame transfer CCD			
Effective nur	nber of piz	xels	640 (H) × 480 (V)			
Cell size			14 μm (H) × 14 μm (V)			
Effective are	а		8.96 mm (H) × 6.72 mm (V)			
Frame rate	1×1		31.4 frames/s			
	binning	2×2	58.3 frames/s			
		4×4	101.8 frames/s			
Readout noi:	se (r.m.s.)	(typ.)	Approx. 100 electrons			
Full well cap	acity (typ.	)	30 000 electrons			
Cooling method			Passive air-cooled			
Cooling temp	perature		+ 5 °C (room temperature + 20 °C)			
A/D converte	ər		12 bit			
Exposure tin	ne		30.8 ms to 1 s			
Analog gain			Approx. 1 to 5 times (16 steps)			
Sub-array			8 pixels increments (V)			
External trigg	ger mode		Edge trigger, Level trigger, Start trigger, Synchronous readout trigger			
Image proce	ssing fund	ctions	Background subtraction, Recursive filter			
Lens mount			C-mount			
Interface			Camera Link Base Configuration			
External con	trol		Camera Link			
Power requir	rements		DC +12 V			
Power consu	umption		Approx. 10 V·A			
Ambient storage temperature			- 10 °C to + 50 °C			
Ambient operating temperature			0 °C to + 40 °C			
Ambient stora	ge/operatir	ng humidity	70 % max. (with no condensation)			

OPTIONS

# AC adaptor: A3472-06

Power cable (5 m): A9071-05

\*Calculated from the ratio of the full well capacity and the average readout noise.

#### DIMENSIONAL OUTLINES (Unit: mm)



#### ★ Product and software package names noted in this documentation are trademarks or registered trademarks of their respective manufacturers.

- Subject to local technical requirements and regulations, availability of products included in this promotional material may vary. Please consult your local sales representative. Information furnished by HAMAMATSU is believed to be reliable. However, no responsibility is assumed for possible inaccuracies or omissions.
- Specifications and external appearance are subject to change without notice.
- © 2010 Hamamatsu Photonics K.K.

#### $\wedge$ Δ $\wedge$

#### HAMAMATSU PHOTONICS K.K., Systems Division

#### Homepage Address http://www.hamamatsu.com

812 Joko-cho, Higashi-ku, Hamamatsu City, 431-3196, Japan, Telephone: (81)53-431-0124, Fax: (81)53-435-1574, E-mail:export@sys.hpk.co.jp U.S.A. and Canada: Hamamatsu Corporation: 360 Foothill Road, Bridgewater, N.J. 08807-0910, U.S.A., Telephone: (1) 908-231-0960, Fax: (1)908-231-0852, E-mail: usa@hamamatsu.com Germany: Hamamatsu Photonics Deutschland GmbH: Arzbergerstr. 10, D-82211 Herrsching am Ammersee, Germany: Telephone: (49)8152-375-0, Fax: (49)8152-2668, E-mail: inde Amamatsu de France: Hamamatsu Photonics France S.A.R.L: 19, Rue du Saule Trapu, Parc du Moulin de Massy, 91882 Massy Cedex, France, Telephone: (49)8152-371 00, Fax: (33)1 69 53 71 00, Fax: (33)1 69 53 71 10, E-mail: infos@hamamatsu.rf United Kingdom: Hamamatsu Photonics UK Limited: 2 Howard Court, 10 Tewin Road, Welwyn Garden City, Hertfordshire, AL7 1BW, U.K., Telephone: (44) 1707-294888, Fax: (44) 1707-325777, E-mail: info@hamamatsu.ce.uk North Europe: Hamamatsu Photonics Norden AB: Smidesvägen 12, SE-171-41 Solna, Sweden, Telephone: (46)8-509-031-00, Fax: (46)8-509-031-01, E-mail: info@hamamatsu.se Cat. No. SCAS0009E01 Italy: Hamamatsu Photonics Italia S.R.L.; Strada della Moia. 1 int.6-20020 Arese (Milano). Italy. Telephone; (39)02-935 81 733, Fax; (39)02-935 81 741. E-mail: info@hamamatsu.it

JUN/2010 HPK Created in Japan